

ABSTRACT OF THE DISCLOSURE

An image sensor module and a method for manufacturing the same. The image sensor module includes a substrate, a photosensitive chip mounted to the substrate, a plurality of wires for electrically connecting the photosensitive chip to the substrate, a frame layer mounted to the substrate to surround the photosensitive chip, and a lens barrel formed with a chamber at a center thereof and an external thread at an outer edge thereof. An inner edge of the frame layer is formed with an internal thread, and a transparent layer is fixed by the frame layer such that the photosensitive chip may receive optical signals passing through the transparent layer. The external thread is screwed to the internal thread of the frame layer. The lens barrel has a through hole and an aspheric lens from top to bottom.